



EV GROUP®
**PROCESS
SERVICES**



EVG at a Glance

Our comprehensive process knowledge is a result of our decades of experience. This knowledge creates benefits and advantages for our customers from the early stages of process development to the final goal of high-volume production.

With state-of-the-art application labs at our headquarters in Austria, along with the United States and Japan, EV Group is focused on delivering superior process expertise to our growing global customer base every step of the way. We can provide support for initial development through final integration at the customer's site.

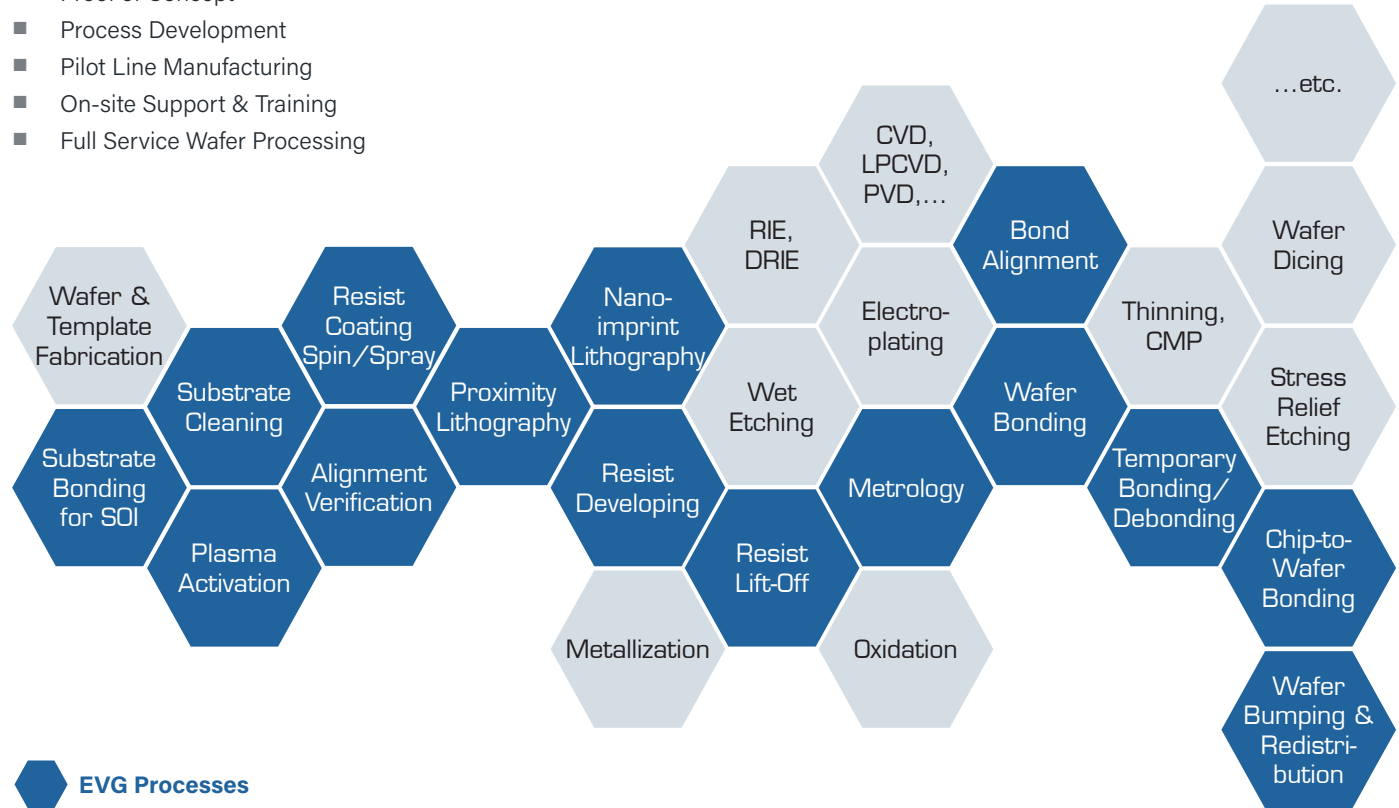
Process know-how is key to achieving the shortest time to market for your product. EV Group is a global supplier to:

- Advanced Packaging & 3D Interconnect
- MEMS
- SOI & Engineered Substrates
- Compound Semiconductor and Silicon-based Power Devices
- Nanotechnology



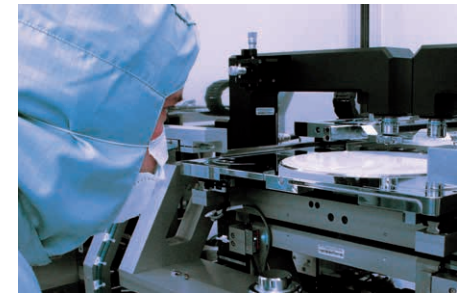
EVG Process Expertise

- Proof of Concept
- Process Development
- Pilot Line Manufacturing
- On-site Support & Training
- Full Service Wafer Processing



EVG Processes

EVG's worldwide application labs focus on demonstrating and developing processes within our core competencies of wafer bonding, lithography and metrology. We provide access to other key processing steps through our preferred partner network around the globe. Please contact us and let EVG be your total process service solution provider.



EVG's Process Services

EVG process engineering provides full service wafer processing.

Our experienced team of process, application and equipment engineers supports samples processing, design of experiments and process optimization.

EVG's application labs provide the industry's most advanced equipment in ISO 4 and ISO 5 environments with a professional setting and infrastructure for wafer processing.

Benefits

- Processing by leading experts
- No capital expenditure required
- Access to state-of-the-art equipment
- Small batch sizes possible
- Capability to process wafers from 2" to 300 mm
- High success rate for sample processing
- Reliable scheduling and fast execution
- Access to EVG's partner service providers
- All EVG unit operations can be utilized in any lab



Cleanroom at EVG headquarters

EV Group Global Locations Application Laboratories

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